



Heavy Wire bonding – detailed view

F & K DELVOTEC Bondtechnik GmbH, the innovation leader in wire bonding, was founded in 1978 and has since then pioneered the development of new technologies that have subsequently progressed to become market standards. Until now F & K DELVOTEC won over 40 patents worldwide, and successfully delivered over 6.000 wire bonding machines to major accounts within the semiconductor, electronics and automotive industries. As specialists for assembly and joining technologies we have been committed to continuing to develop reliable and efficient solutions for connecting electronic components. In the field of wire bonding for customers in the semiconductor, E-Mobility, Photo-Voltaic and automotive industries, F & K DELVOTEC develops complete solutions for partial or full automation. The all-round

service ranges from applications guidance in the selection and configuration of the wire bonding machines to attached buffer stations and magazine lifts all the way to the integration of handling systems for complex production lines. The standard portfolio covers bonding equipment in fine, ball/wedge and heavy bonding technology. The boom in the market for power electronics continues unabated. Because of the physical limits to the current carrying capacity of wire bonded connections, F & K DELVOTEC developed a robust and extremely reliable technology for joining aluminum and copper ribbons on DCB and other substrates: laser bonding. Already at the product development stage, F & K DELVOTEC is ready to help with pre-trials to evaluate the bondability of material surfaces, and with product design.

This is of great value in Design for Manufacturability, shortens the development time and optimizes the process of adding value from the start.

Only the best trained personnel can extract the best from bonding technology. That's why we support our customers during the complete lifetime of any F & K DELVOTEC wire bonder with a range of services in our Bond Academy. These run from applications advice through support during the product development to training classes regarding wire bonding in general and the machine operation. F & K DELVOTEC offers applications support, sample bonding, bond quality measurements and training throughout the lifetime of the wire bonders.

With our bonding experts the semiconductor industry, the automotive industry and other highly innovative electronic branches are in safe hands.



Ultrasonic Heavy Wire Bonder M17